

SIL35-HXP Form-In-Place



SIL35-HXP FORM-IN-PLACE

A non-slump, single component, high flexibility, thermally curable silicone rubber.

Laird Technologies' Form-In-Place is an automated system for dispensing non-conductive and conductive elastomer EMI shielding and grounding gaskets onto metal substrates. This product is particularly ideal for base stations, PDAs, PC cards, radios, and mobile phones, as well as many other cast enclosures and packaged electronic assemblies

TYPICAL VALUES

CATEGORIES	TEST METHOD	UNITS	SIL35-HXP
Elastomer			Silicone
COLOR			Transparent
PHYSICAL PROPERTIES			
Hardness	ASTM D2240	Shore A	35
Density (cured)	ASTM D792	g/cm ³	1.2
Tensile Strength	ASTM D412	MPa	4.5
Compression Set	ASTM D395	%	20
Adhesion Strength (Al)	LT-FIP-CLE-03		285
Compression-Deflextion (a)	LT-FIP-CLE-07		
at 20% compression		lb/in	4.1
at 40% compression		lb/in	11.7
CURING REQUIREMENTS			
Minimum Temperature		120°C	
125°C, One Hour		Full Cure	

(a) Compression-deflection bead size $0.6mm (H) \times 0.7mm (W)$

(b) Time to effectively cure a bead will necessarily depend on individual conditions, including but not limited to bead size, shield size and weight, oven capacity, and oven ramp-rates.



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EMI-DS-SIL35-HXP

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